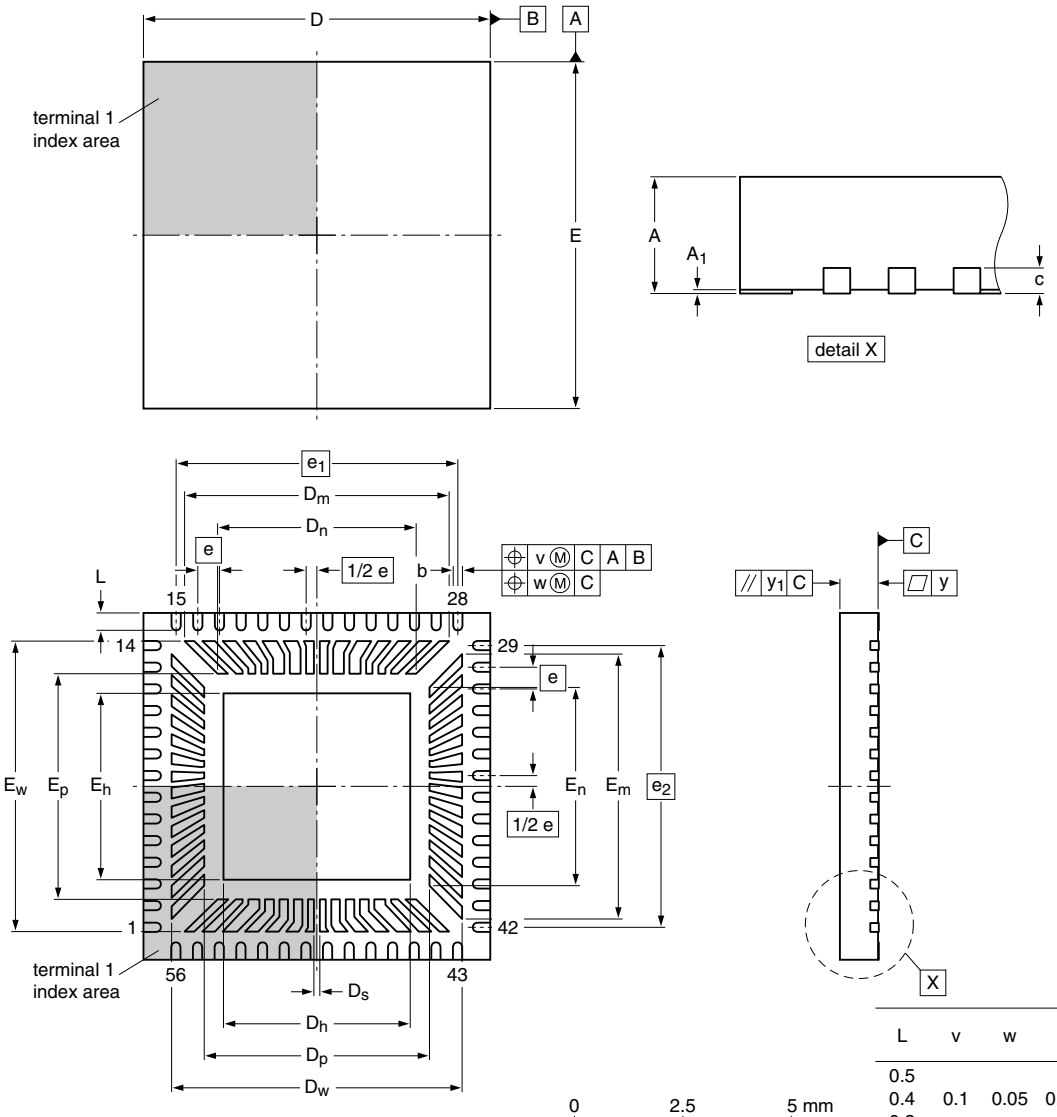
Package outline

HVQFN56: plastic thermal enhanced very thin quad flat package; no leads; 56 terminals; body 8 x 8 x 0.85 mm **SOT684-9**



L	v	w	y	y_1
0.5 0.4 0.3	0.1	0.05	0.05	0.1

Dimensions

Unit		$A^{(1)}$	A_1	b	c	$D^{(1)}$	D_h	D_m	D_n	D_p	D_s	D_w	$E^{(1)}$	E_h	E_m	E_n	E_p	E_s	E_w	e	e_1	e_2
mm	max	1.00	0.05	0.30	0.2	8.1	4.45	6.158	4.625	5.25	0.18	6.75	8.1	4.45	6.158	4.625	5.25	0.18	6.75	0.5	6.5	6.5
	nom	0.85	0.02	0.21		8.0	4.30	6.108	4.575	5.20	0.13	6.70	8.0	4.30	6.108	4.575	5.20	0.13	6.70			
	min	0.80	0.00	0.18		7.9	4.13	6.058	4.525	5.15	0.08	6.65	7.9	4.15	6.058	4.525	5.15	0.08	6.65			

Note
1. Plastic or metal protrusions of 0.075 mm per side are not included.

sot684-9_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT684	- - -	- - -	- - -		~~09-03-20~~ 09-05-25

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